

Form PTO-1449	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DKT. NO. 501.36636CC3	SERIAL NO. TBD
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b> <small>(Use several sheets if necessary)</small>		APPLICANT KONDO, et al.	
		FILING DATE April 16, 2004	GROUP 2812

**U.S. PATENT DOCUMENTS**

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
BT	AA	5,858,813	1-12-99	Scherber, et al.	438	693
	AB	5,866,031	2-2-99	Carpio, et al.	252	79.1
	AC	5,840,629	11-24-98	Carpio	438	692
	AD	5,783,489	7-21-98	Kaufman, et al.	438	692
	AE	5,759,917	6-2-98	Grover	438	690
	AF	5,733,176	3-31-98	Robinson, et al.	451	41
	AG	5,695,660	12-9-97	Litvak	216	85
	AH	5,676,760	10-14-97	Aoki, et al.	134	1.3
BT	AI	4,944,836	6-90	Beyer, et al.		
	AJ					
	AK					
	AL					

**FOREIGN PATENT DOCUMENTS**

Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No
	AM						
	AN						
	AO						
	AP						
	AQ						
	AR						
	AS						
	AT						

**OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)**

BT	AU	"Pattern Geometry Effects in the Chemical-Mechanical Polishing of Inlaid Copper Structures", J. Electrochem. Soc., vol. 141, p. 2842-2848, October 10, 1994.
BT	AV	"An Examination of Slurry for Wiring Metal's Chemical-Mechanical Polishing", vol. 41, p. 35-37, June 1997 (in Japanese)
	AW	"Semiconductor International", Semiconductor World, p. 171-172, May 1995 (in Japanese)
	AX	"Electrochemical Potential Measurements during the Chemical-Mechanical Polishing of Copper Thin Films", J.E. Electrochem. Soc., vol. 142, July 7, 1995 p. 2379-2385.
BT	AY	"Chemical Mechanical Polishing of Copper using a Slurry composed of glycine and hydrogen peroxide", CMP-MIC Conferences 1996 ISMIC, February 22-23, 1996, CMP p. 119-123.
BT	AZ	Kashiwagi, The Science of CMP (1997), p. 299-300.

Examiner  /Binh Tran/	Date Considered  06/05/2006
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<b>FORM PTO-1449 U.S. Department of Commerce (Rev. 4/92) Patent and Trademark Office</b>		<b>ATTY. DOCKET NO.</b> <u>501.36636CC3</u>	<b>SERIAL NO.</b> <u>TBD</u>
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(Name, Address, Date, Permanent Pages, Etc.)

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**EXAMINER:** Initial If citation is considered, draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.